

ABSTRACT

Provided is a method of peeling an electronic member
5 (16) from a laminate (10) composed of the electronic member
(16) adhered to a supporting substrate (12) via an adhesive
film (14), the adhesive film (14) having a self-peeling
adhesive layer (17) on a surface located on the side of the
supporting substrate (12) and an exposed region A in at least
10 one part of a surface (14a) which is located on the side of
the electronic member (16). The method includes: a step of
reducing adhesive strength between the supporting substrate
(12) and the self-peeling adhesive layer (17) in the region
A by applying energy on the region A; a step of removing the
15 supporting substrate (a) from the laminate by further
applying energy on the region and thus further reducing the
adhesive strength reduced in the prior step between the
supporting substrate (a) and the self-peeling adhesive layer
from a starting point of the interface between the supporting
20 substrate (a) and the self-peeling adhesive layer; and a step
of peeling the electronic member (16) from the laminate by
removing the adhesive film (14) from the electronic member
(16).